

PMP10900 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C5	2	0.1uF	GRM155R61C104KA88D	MuRata	CAP, CERM, 0.1 μ F, 16 V, +/- 10%, X5R, 0402	0402
C2, C3, C4	3	22uF	GRM21BR61A226ME44	MuRata	CAP, CERM, 22 μ F, 10 V, +/- 20%, X5R, 0805	0805
C6	1	22uF	C1608X5R0J226M080AC	TDK	CAP, CERM, 22 μ F, 6.3 V, +/- 20%, X5R, 0603	0603
C7	1	100uF	GRM31CR60J107ME39L	MuRata	CAP, CERM, 100 μ F, 6.3 V, +/- 20%, X5R, 1206	1206
C8	1	0.01uF	GRM155R71H103KA88D	MuRata	CAP, CERM, 0.01 μ F, 50 V, +/- 10%, X7R, 0402	0402
C9	1	4700pF	GRM155R71H472KA01D	MuRata	CAP, CERM, 4700 pF, 50 V, +/- 10%, X7R, 0402	0402
C10	1	470pF	GRM155R71H471KA01D	MuRata	CAP, CERM, 470 pF, 50 V, +/- 10%, X7R, 0402	0402
L1	1	1uH	PIMB065T-1R0	Cyntec	Inductor, Drum Core, Ferrite, 1 μ H, 13 A, 0.0056 ohm, SMD	7.05x4.8x6.6mm
L2	1	220nH	IHLP1212ABERR22M11	Vishay-Dale	Inductor, Shielded Drum Core, Powdered Iron, 220 nH, 9.3 A, 0.0114 ohm, SMD	3.0x1.2x3.0mm
R1	1	1.0	CRCW08051R00JNEA	Vishay-Dale	RES, 1.0, 5%, 0.125 W, 0805	0805
R2	1	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
R3	1	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
R4	1	10k	CRCW040210K0JNED	Vishay-Dale	RES, 10 k, 5%, 0.063 W, 0402	0402
R5	1	90.9k	CRCW040290K9FKED	Vishay-Dale	RES, 90.9 k, 1%, 0.063 W, 0402	0402
R6	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R7	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R8	1	53.6k	CRCW040253K6FKED	Vishay-Dale	RES, 53.6 k, 1%, 0.063 W, 0402	0402
U1	1		TPS54678RTER	Texas Instruments	2.95 V to 6 V INPUT, 6 A OUTPUT, 2 MHz, SYNCHRONOUS STEP DOWN SWITCHER WITH INTEGRATED FET (SWIFT™), RTE0016F	RTE0016F

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